

Form PTO-1449 (modified)

Atty. Docket No.  
102-0118US2Serial No.  
09/740,751

**List of Patents and Publications for Applicant's  
INFORMATION DISCLOSURE STATEMENT**

(Use several sheets if necessary)

Inventor/Applicant:  
Tongbi Jiang et al. / Micron Technology, Inc.Title: Method for Forming Novel Zero Force  
Insertion Sockets Using Negative Thermal  
Expansion Materials (as amended previously)

Filing Date: 12/19/00 Group: 3729

**U.S. Patent Documents**

Exam. Init.	Ref. Des.	Document Number	Date	Name	Class	Sub Class	Filing Date of App.
RC	A1	4,513,055	Apr. 23, 1985	Leibowitz	428	245	
	A2	6,274,932	Aug. 14, 2001	Mikagi	257	754	
	A3	6,187,700	Feb. 13, 2001	Merkel	501	32	
	A4	5,497,545	Mar. 12, 1996	Watanabe et al.	29	830	
	A5	5,919,720	Jul. 6, 1999	Sleight et al.	501	126	
	A6	5,641,291	Jun. 24, 1997	Sueki et al.	439	83	
	A7	4,950,173	Aug. 21, 1990	Minemura et al.	439	82	
	A8	5,607,313	Mar. 4, 1997	Nyman	439	83	
	A9	5,123,849	Jun. 23, 1992	Deak et al.	439	66	
	A10	5,387,121	Feb. 7, 1995	Kurz	439	342	
↓	A11	5,433,778	Jul. 18, 1995	Sleight	106	401	RECEIVED AUG 18 2004 TECHNOLOGY CENTER 23700
	A12	5,514,360	May 7, 1996	Sleight et al.	423	593	
RC	A13	5,466,169	Nov. 14, 1995	Lai	439	264	

**Foreign Patent Documents**

Exam. Init.	Ref. Des.	Document Number	Date	Country	Class	Sub Class	Translation Yes/No
	B1						

**Other Art (Including Author, Title, Date Pertinent Pages, Etc.)**

Exam. Init.	Ref. Des.	Citation
RC	C1	T.A. Mary et al., "Negative Thermal Expansion from 0.3 to 1050 Kelvin in ZrW <sub>2</sub> O <sub>8</sub> ," <i>Science</i> , Vol. 272, pp. 91-93 (Apr. 5 1996).
RC	C2	Anonymous, "Siemens Demonstrates Fingertip Chip Sensor," <i>Semiconductor International</i> , pp. 33-34 (Apr. 1998).

EXAMINER:

/Rick Chang/

DATE CONSIDERED: 10/03/2006

EXAMINER: INITIAL IF REFERENCE CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED. INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.